PATENT

IFW

OIPE
NOV 0 4 2004
PATENT & TRADEMARK OFFICE

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos KARNEZOS

Application No.: 10/681,734

Filed: October 8, 2003

Title: **Semiconductor multi-package module having inverted bump chip carrier second package**

Examiner: Alonzo Chambliss

Group Art Unit: 2827

Date: November 1, 2004

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: Mail Stop Amendment, Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on November 1, 2004.

Signed _____
Paula Faulk Hurley

MAIL STOP AMENDMENT
COMMISSIONER FOR PATENTS
P.O BOX 1450
ALEXANDRIA, VA 22313-1450

AMENDMENT

Dear Sir:

In response to the Office action mailed July 28, 2004, kindly amend the application as follows.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the claims are reflected in the **Listing of Claims** that begins on page 5 of this paper.

Amendments to the Drawings begin on page 7 of this paper and include both attached replacement sheets and an annotated sheets showing changes.

Remarks begin on page 8 of this paper.

An **Appendix** including amended drawing figures is attached following page 13 of this paper.